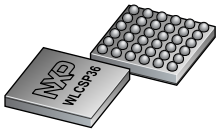
SOT1780-14

WLCSP36, wafer level chip-size package, 36 terminals, 0.4 mm pitch, 2.46 mm x 2.46 mm x 0.525 mm body

11 May 2026 Package information



1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	WLCSP36
Package style descriptive code	WLCSP (wafer level chip-size package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	05-05-2026
Manufacturer package code	98ASA02052D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.43	2.46	2.49	mm
package width	2.43	2.46	2.49	mm
seated height	0.485	0.525	0.565	mm
package height	0.335	0.365	0.395	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	36	-	

2 Package outline

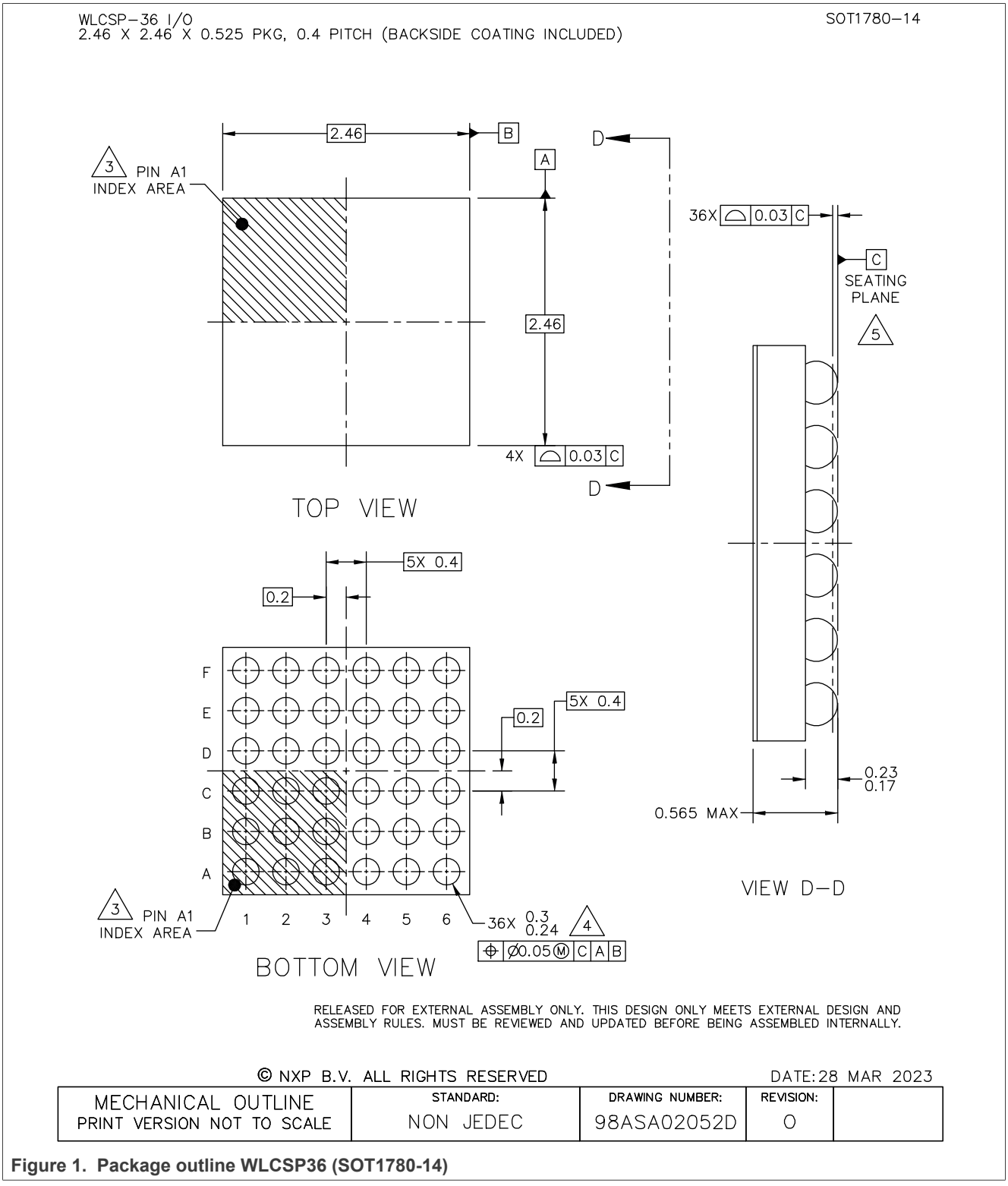


Figure 1. Package outline WLCSP36 (SOT1780-14)

3 Soldering

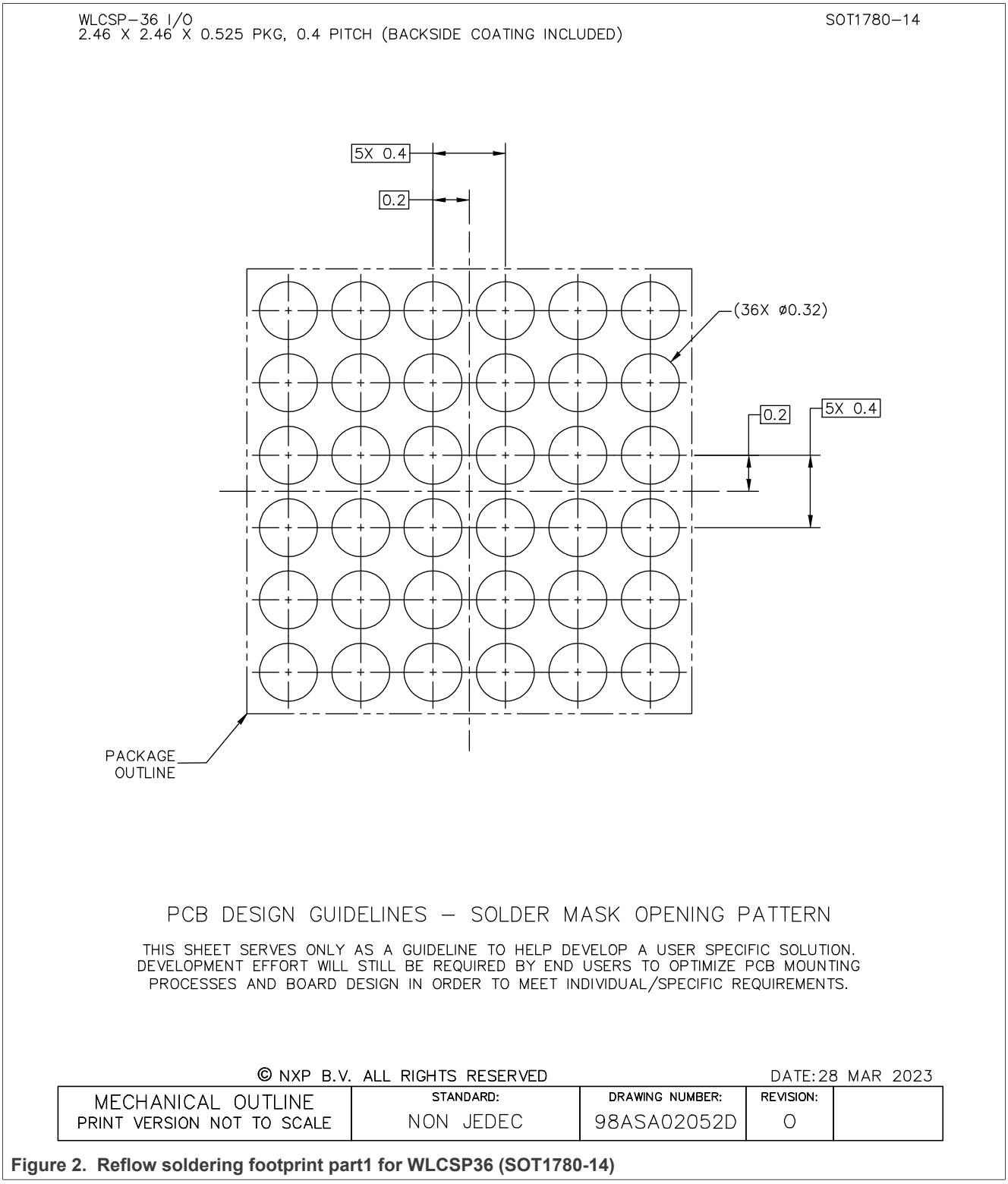


Figure 2. Reflow soldering footprint part1 for WLCSP36 (SOT1780-14)

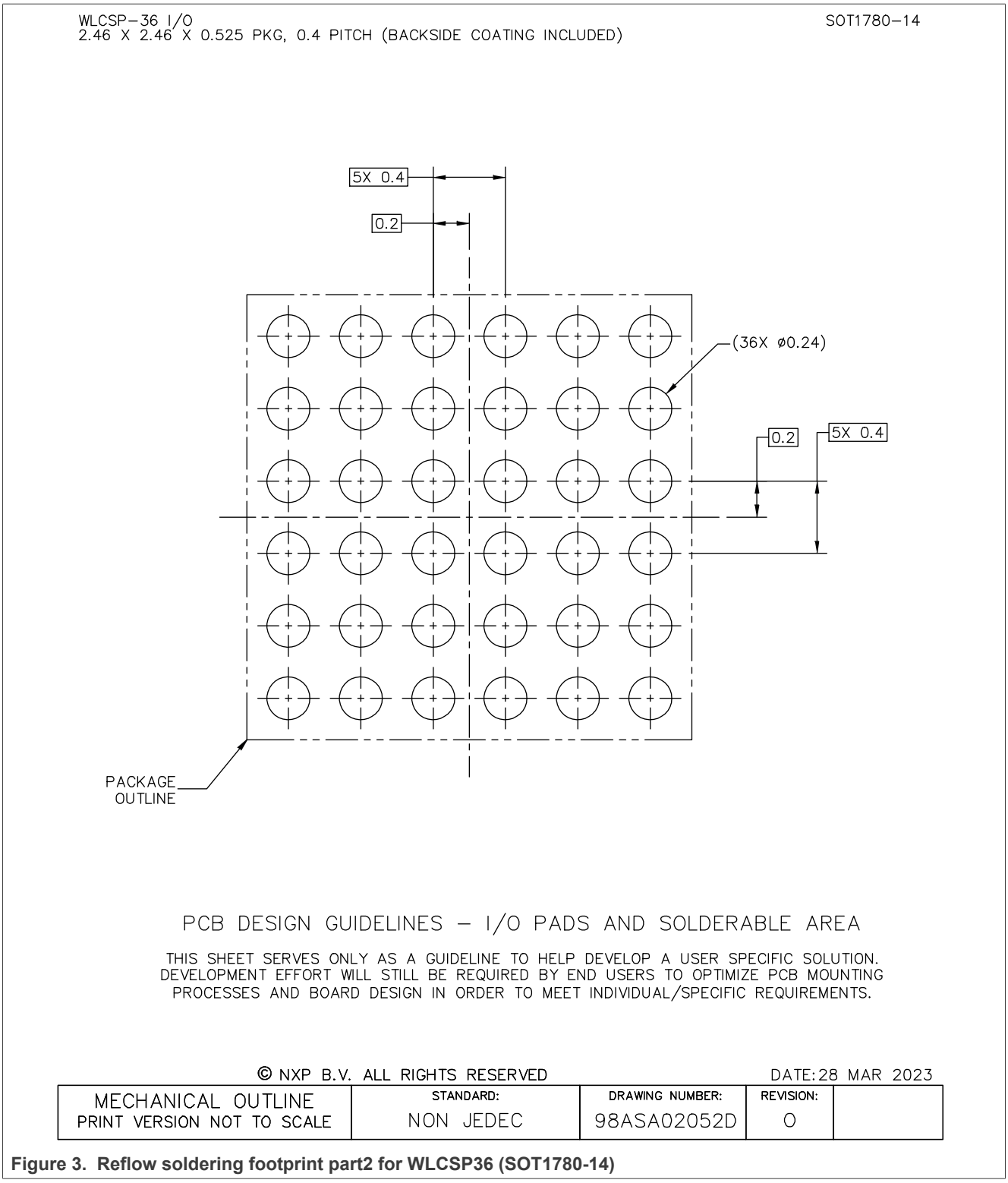
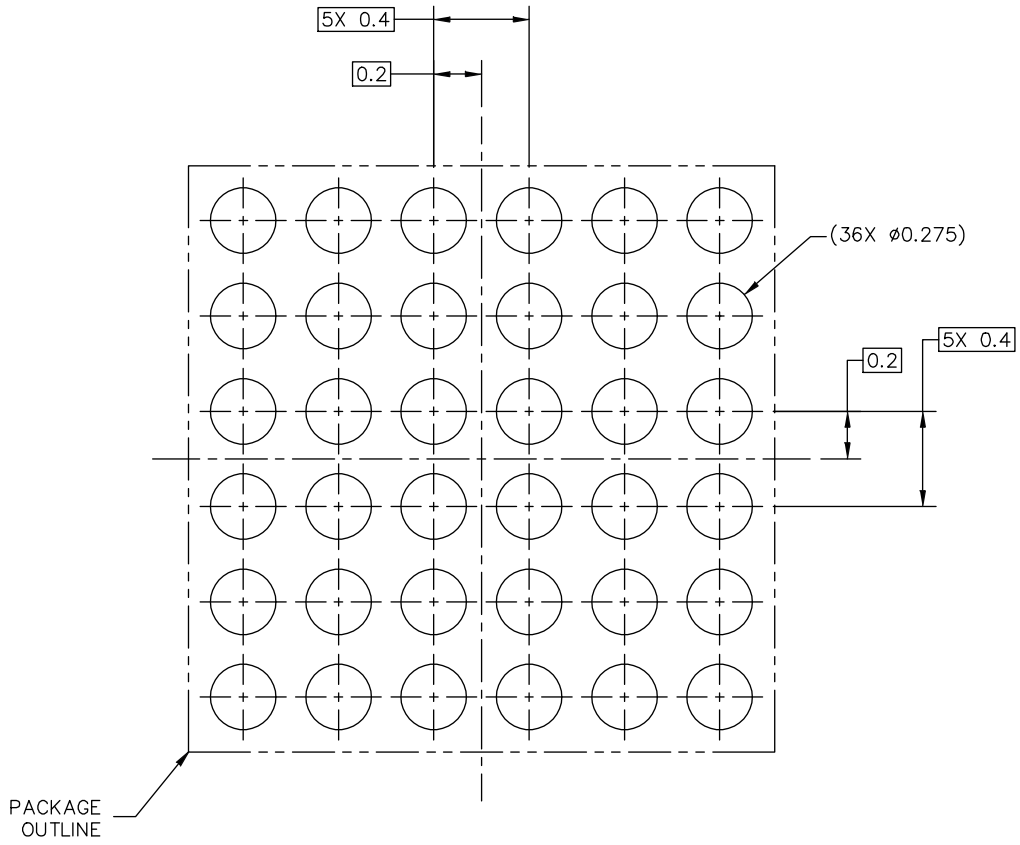


Figure 3. Reflow soldering footprint part2 for WLCSP36 (SOT1780-14)

WLCSP−36 I/O
2.46 X 2.46 X 0.525 PKG, 0.4 PITCH (BACKSIDE COATING INCLUDED)

SOT1780−14



RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES − SOLDER PASTE STENCIL

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

DATE: 28 MAR 2023

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA02052D	REVISION: O	

Figure 4. Reflow soldering footprint part3 for WLCSP36 (SOT1780-14)

WLCSP36, wafer level chip-size package, 36 terminals, 0.4 mm pitch, 2.46 mm x 2.46 mm x 0.525 mm body

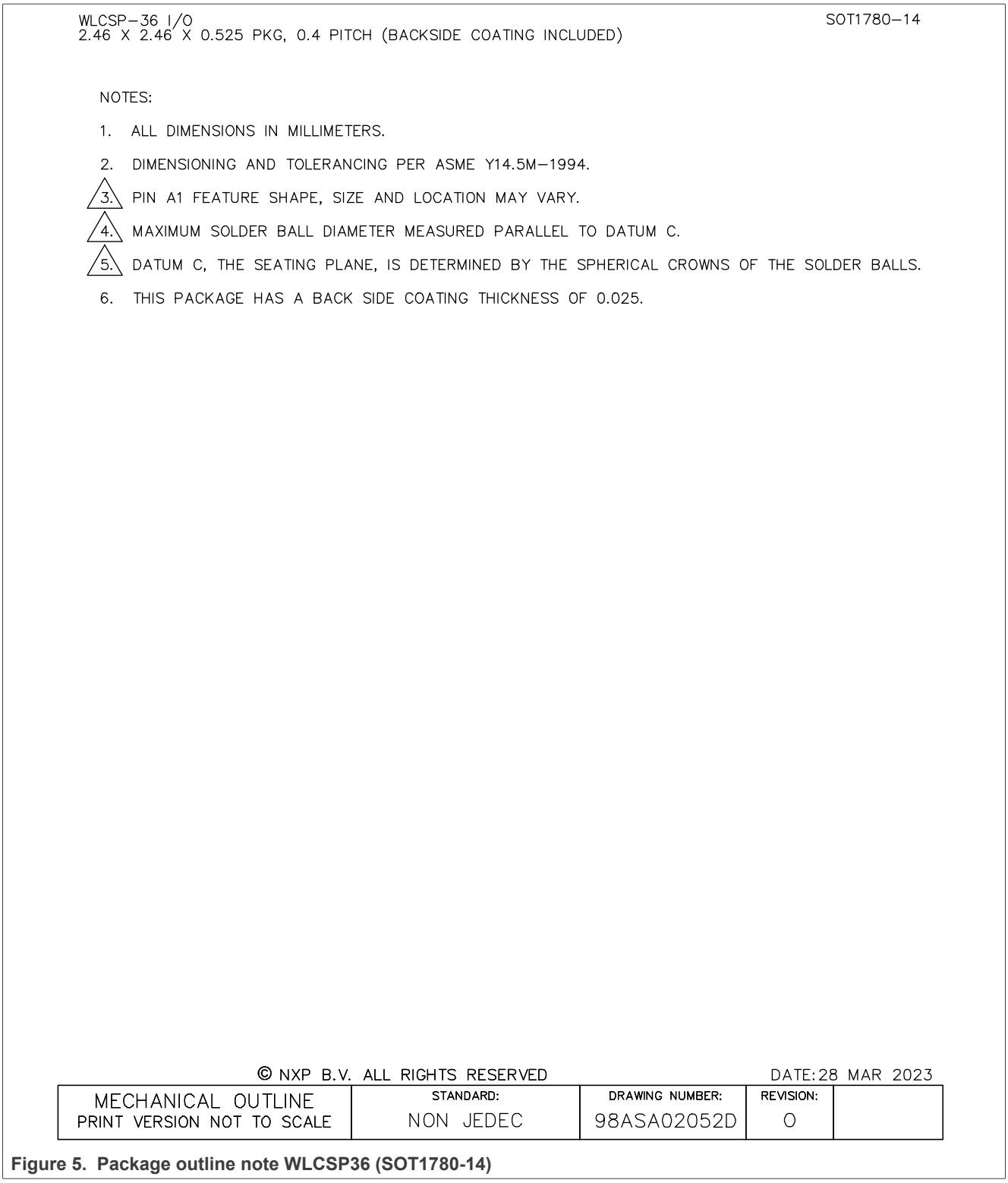


Figure 5. Package outline note WLCSP36 (SOT1780-14)

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